APPLIC	ABL	E STAN	DARD									
OPERATING TEMPERATU			E RANGE	-35°C TO +85°C(NOTE 1)		TEM	PRAGE IPERATURE RANGE		E	-10°C TO +60°C(NO		3)
RATING	HUI	OPERATING HUMIDITY RANGE		20 % TO 80 % (NO	OTE 2)	HUM	RAGE			40 % TO 70 %(NO	TE 3	3)
	vC	VOLTAGE		150 V AC	150 V AC cor			ર		DF13-*S-1.25	-	
	CL	CURRENT		4 4			PLICABLE MP CONTACT			DF13(G)-2630SCF DF13-3032SCF		
				SPEC	IFICA		NS					
ITEM			TEST METHOD				REQUIREMENTS				QT	AT
						-						
GENERAL EXAMINATION MARKING			VISUALLY AND BY MEASURING INSTRUMENT.				ACCORDING TO DRAWING.				X	X
-		CHARA									~	
CONTACT RESISTANCE			100 m A (DC OR 1000 Hz).				30 mΩ MAX.					-
INSULATION			100 V DC.				500 MΩ MIN.				х	_
RESISTANCE VOLTAGE PROOF			500 V AC FOR 1 min.				NO FLASHOVER OR BREAKDOWN.				X	_
MECH	ANIC		RACTE	ERISTICS			_		-		Λ	
MECHANICAL OPERATION			30 TIMES INSERTIONS AND EXTRACTIONS.				 CONTACT RESISTANCE: 30 mΩ MAX. NO DAMAGE, CRACK OR LOOSENESS OF PARTS. 				x	_
VIBRATION			FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE							DISCONTINUITY OF 1µs.		_
SHOCK			0.75 mm, AT 2 h, FOR 3 DIRECTIONS. 490 m/s ² DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.				② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.				X X	-
ENVIR	ONM	IENTAL	CHAR/	ACTERISTICS			I					
RAPID CH	-	OF		ATURE -55 \rightarrow 5 TO 35 \rightarrow +85-		-	~			ANCE: 30mΩ MAX.		
TEMPERATURE			TIME $30 \rightarrow 10 \text{ TO } 15 \rightarrow 30 \rightarrow 10 \text{ TO } 15 \text{ min.}$ UNDER 5 CYCLES.EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.				 2 INSULATION RESISTANCE: 500 MΩ MIN. 3 NO DAMAGE, CRACK OR LOOSENESS OF PARTS. 				Х	-
(STEADY STATE)		E)					174				Х	—
RESISTANCE TO SOLDERING HEAT			 1) REFLOW SOLDERING ≪REFLOW AREA≫ 250°C MAX 10 sec MAX 230°C MIN 60 sec MAX ≪PREHEATING AREA≫ 170°C TO 190°C 60 sec TO 120 sec PUT THROUGH IN REFLOW FURNACE TWICE, LEAVE IN AMBIENT TEMPERATURE AND HUMIDITY FOR 1 HOUR. 2) MANUAL SOLDERING SOLDERING IRON TEMPERATURE :350°C, SOLDERING TIME : 3sec. NO STRENGTH ON CONTACT. Output 10 sec MAX • Control 100°C 10 sec MAX • Control 100°C 100°C 100°C 100°C • Control 100°C 100°C 100°C 100°C • Control 100°C 100°C 100°C 10°C • Control 100°C 100°C 100°C 100°C 100°C 100°C 100°C • Control 100°C 100°C				NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.				x	
SOLDERABILITY			SOLDERED AT SOLDER TEMPERATURE, 245°C FOR INSERTION DURATION, 3sec.				SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED.					_
NOTE2: NO NOTE3: AF AF	CLUDE CONE PPLY TO TER N	DENSING D THE CONI	ERATURE	RISING BY CURRENT LONG TERM STORAGE FOR DARD, OPERATING TEMPER	UNUSED P		TS BEFO	DRE MOUI	NTED	ON PCB.	GE DI	URIN
COL	JNT	DE	SCRIPTIC	ON OF REVISIONS		DESIG	SNED			CHECKED		ΔTE
Unless otherwise specified, refer to IEC 60512.							APPROVE					14 05
	other							-		HS.OKAWA)4.05
	other	wise spec	sineu, re					CHECK	ED L	TS.FUKUSHIMA	18.0	J4.UN
	other	wise spec	uneu, re					CHECK		TS.FUKUSHIMA TS.KUMAZAWA	18.0 18.0	
	other								IED		18.0)4.05
Unless				surance Test X:Applicable	Test	DF	RAWIN	DESIGN DRAW	IED	TS.KUMAZAWA	18.0 18.0)4.05)4.05
Unless	Qualif	fication Tes	st AT:As		Test	DF		DESIGN DRAW	NED /N	TS.KUMAZAWA MK.INOUE	18.0 18.0)4.05)4.05